



Material Content Data Sheet



Sales Product Name		IPU50R1K4CE		Issued		20. July 2018		
MA#		MA001476394						
Package		PG-TO251-3-345		Weight*		384.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.378	0.36	0.36	3581	3581
leadframe	non noble metal	iron	7439-89-6	0.209	0.05		542	
	inorganic material	phosphorus	7723-14-0	0.063	0.02		162	
	non noble metal	copper	7440-50-8	208.238	54.09	54.16	540886	541590
wire	non noble metal	aluminium	7429-90-5	4.631	1.20	1.20	12028	12028
encapsulation	organic material	carbon black	1333-86-4	0.684	0.18		1777	
	plastics	epoxy resin	-	18.468	4.80		47970	
	inorganic material	silicondioxide	60676-86-0	117.650	30.56	35.54	305589	355336
leadfinish	non noble metal	tin	7440-31-5	7.055	1.83	1.83	18324	18324
solder	noble metal	silver	7440-22-4	0.043	0.01		111	
	non noble metal	tin	7440-31-5	0.034	0.01		89	
	non noble metal	lead	7439-92-1	1.631	0.42	0.44	4236	4436
heatspreader	non noble metal	iron	7439-89-6	0.025	0.01		65	
	inorganic material	phosphorus	7723-14-0	0.007	0.00		19	
	non noble metal	copper	7440-50-8	24.879	6.46	6.47	64621	64705
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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